

24TH IEEE International NEWCAS Conference

An IEEE CASS flagship conference

June 21–24, 2026
SAGUENAY, QUÉBEC, CANADA



CHICOUTIMI, QUÉBEC
NEWCAS
20  26

The 24th IEEE International NEWCAS Conference will take place in Saguenay, Canada, from June 21 to 24, 2026. The conference will showcase a wide range of topics, research, and practical advancements in the field of circuits and systems, providing an international platform for exchanging ideas and findings. Attendees can also look forward to tutorials, special sessions, and keynote presentations by leading experts on cutting-edge topics in microsystems research.

AUTHORS SCHEDULE

DEADLINE for full paper submission:

February 9, 2026

DEADLINE for tutorial and special session proposals:

February 16, 2026

NOTIFICATION of acceptance:

April 10, 2026

SUBMISSION DEADLINE of final manuscript:

May 10, 2026

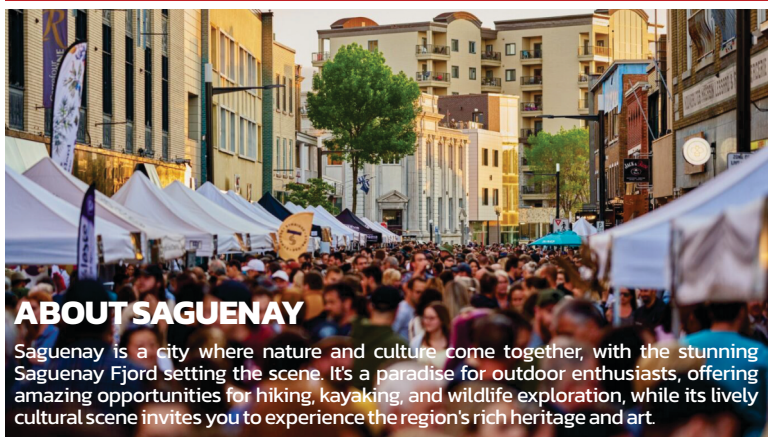
SUBMISSION

Only electronic submissions will be considered. Papers must be four pages long and follow the standard IEEE double-column conference format. Submissions should be in PDF format and compliant with IEEE Xplore requirements. Accepted technical and special session papers will be published in the IEEE Xplore Digital Library.

For detailed information on the proposal and paper submission process, please refer to the conference website:
newcas2026.org



CALL FOR PAPERS



ABOUT SAGUENAY

Saguenay is a city where nature and culture come together, with the stunning Saguenay Fjord setting the scene. It's a paradise for outdoor enthusiasts, offering amazing opportunities for hiking, kayaking, and wildlife exploration, while its lively cultural scene invites you to experience the region's rich heritage and art.



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THE TOPICS INCLUDE, BUT ARE NOT LIMITED TO

- Analog/Mixed-Signal Circuits
- Biomedical Circuits and Systems
- Digital Circuits and Systems
- Communications Circuits and Systems
- RF & Microwave Circuits
- Photonic Integrated Circuits
- CAD and Design Tools
- Test and Verification
- Energy Harvesting and Power Management
- Low-Power Low-Voltage Designs
- Microsystems, Embedded Systems and IoT
- Circuits and Systems for AI Algorithms
- Neural Networks and Neuromorphic Circuits
- Sensory Circuits and Systems
- Innovative materials and processes for circuits and systems
- Imaging and Image Sensors
- Quantum Computing
- Emerging Technologies and Technology Trends
- Circuits and Systems for Sustainable Development
- Circuits and Systems for Industry 4.0